

MPN3015S Series

Metal Alloy Wire Wound SMD Power Inductors

FEATURES

- Fe base metal material core provides large saturation current
- Metallization on ferrite core results in excellent shock resistance and damage-free durability
- Closed magnetic circuit design reduces leakage flux and Electro Magnetic Interference (EMI)
- Low DCR decreases power loss, small and slim take up less PCB real estate
- Automatic production ensures high quality and consistency
- Operate temperature range $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (Including self temp. rise)
- RoHS compliant



APPLICATIONS

- Smart phone, set top box, VR, AR
- Notebooks, desktop computers, servers
- Portable gaming devices, personal navigation systems, personal multimedia devices

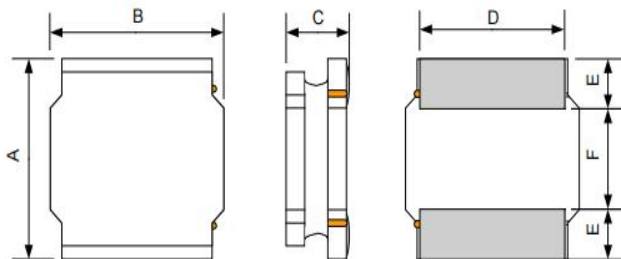
Explanation of Part Number

MPN 3015 S 1R0 M T

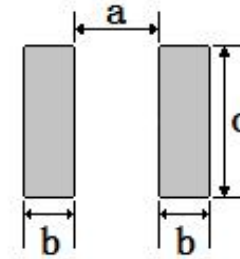
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- ◆ 1:Product Series:Metal Alloy Wire Wound SMD Power Inductors
- ◆ 2:Dimensions:
- ◆ 3: Feature Type:Standard
- ◆ 4: Initial inductance value: 1R0 = 1.0uH
- ◆ 5: Tolerance of Inductance:M:±20%, N:±30%
- ◆ 6:Packing:Tape Carrier Package

SHAPE AND DIMENSIONS [mm]



Recommended Land Pattern



Series	A	B	C	D	E	F	a Typ.	b Typ.	c Typ.
MPN3015S	3.0±0.2	3.0±0.2	1.5 Max.	2.5±0.2	0.9 Typ.	1.2 Typ.	1.00	1.10	2.7

Electrical Characteristics List

Part Number	Inductance	DC Resistance		Isat(A)		Irms(A)	
	1MHz/0.1V	Max.	Typ.	Max.	Typ.	Max.	Typ.
Units	(μ H)	Ω	Ω	A	A	A	A
MPN3015SR24NT	0.24 $\pm$ 30%	0.022	0.018	5.50	6.00	3.00	3.50
MPN3015SR33NT	0.33 $\pm$ 30%	0.035	0.026	9.00	10.00	4.00	4.50
MPN3015SR47NT	0.47 $\pm$ 30%	0.040	0.034	7.50	8.00	3.50	4.00
MPN3015S1R0NT	1.0 $\pm$ 30%	0.048	0.041	5.80	7.00	3.30	3.80
MPN3015S1R5NT	1.5 $\pm$ 30%	0.072	0.065	4.60	5.50	2.20	2.70
MPN3015S2R2MT	2.2 $\pm$ 20%	0.115	0.085	4.00	4.50	2.00	2.30
MPN3015S3R3MT	3.3 $\pm$ 20%	0.175	0.144	3.40	4.00	2.00	2.50
MPN3015S4R7MT	4.7 $\pm$ 20%	0.215	0.176	3.00	3.30	1.80	2.40
MPN3015S6R8MT	6.8 $\pm$ 20%	0.290	0.259	2.00	2.50	1.50	2.00
MPN3015S100MT	10.0 $\pm$ 20%	0.460	0.357	1.50	2.00	1.50	2.00
MPN3015S150MT	15.0 $\pm$ 20%	0.850	0.695	1.40	1.80	1.00	1.20
MPN3015S220MT	22.0 $\pm$ 20%	0.975	0.762	1.15	1.40	0.75	0.90
MPN3015S330MT	33.0 $\pm$ 20%	1.425	1.135	0.78	1.15	0.75	0.85
MPN3015S470MT	47.0 $\pm$ 20%	1.880	1.450	0.65	0.88	0.45	0.58

※1: All test data is referenced to 20°C ambient;

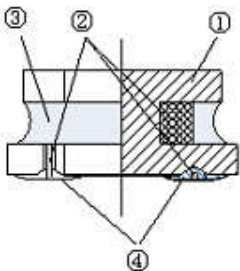
※2: Rated current: Isat or Irms, whichever is smaller;

※3: For MPN3015 size inductors, absolute maximum voltage: DC 25V;

※Isat: DC current at which the inductance drops approximate 30% from its value without current;

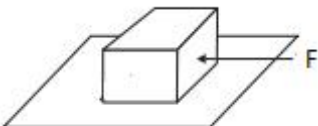
※Irms: DC current that causes the temperature rise ($\Delta T = 40^{\circ}\text{C}$) from 20°C ambient.

Structure

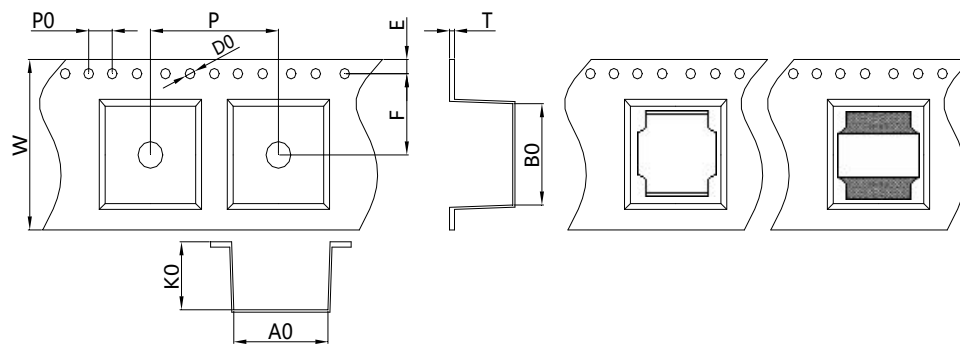


NO.	Components	Material
①	Core	Soft magnetic Metal
②	Wire	Polyurethane system enameled copper wire
③	Magnetic Glue	Epoxy resin and magnetic powder
④	Electrodes	AgNiSn or FeNiCu + Sn Alloy

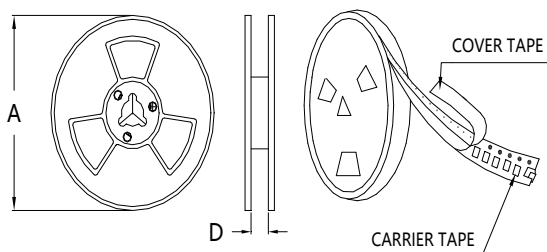
Reliability Test

No.	TEST ITEM	SPECIFICATION	TEST CONDITION
1	High temperature Storage test	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	Temperature: $125^{\circ}\text{C} \pm 5^{\circ}\text{C}$ (N: Follow the product specification for the setting.) Time : 96 ± 2 hours Place the samples for one hour at room temperature and test them within two hours
2	Low temperature Storage test	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	Temperature: $-40^{\circ}\text{C} \pm 5^{\circ}\text{C}$ (M: Follow the product specification for the setting) Time : 96 ± 2 hours Place the samples for one hour at room temperature and test them within two hours.
3	Humidity test	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	Temperature: $40 \pm 2^{\circ}\text{C}$, Humidity: $93 \pm 3\% \text{RH}$ Time : 96 ± 2 hours Place the samples for one hour at room temperature and test them within two hours
4	Solderability test	Terminals must have 95% minimum solder coverage	1. Dip pads in flux then dip in solder pot at $245 \pm 5^{\circ}\text{C}$ for 5 second. 2. Solder: lead free 3. Flux: rosin flux
5	Heat endurance of flow soldering	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	1. Refer to the above reflow curve and go through the reflow for twice. 2. The peak temperature : $260 + 0/-5^{\circ}\text{C}$
6	Vibration test	1. No significant defects in appearance. 2. No short and no open.	Apply frequency 10~55~10Hz and amplitude 1.5mm, 1 min/cycle in X Y and Z direction for 2 hours each. (total 6 hours)
7	Terminal strength push test	1. Applied force: 10N Duration: 10sec 2. Solder paste thickness: 0.12mm 3. Meet the above requirements without any loose termina	Solder the test samples to the PCB through 245°C reflow, apply a standard force on the side of the test samples for 10 seconds. 

PACKAGING SPECIFICATION :



Item	W	A0	B0	K0	P	T	E	F	D0	P0
(mm)	8.0 ±0.3	3.3±0.15	3.3±0.15	2.0 ±0.1	4.0±0.1	0.3±0.1	1.75±0.1	3.5 ±0.1	1.5 ±0.1	4.0 ±0.1



	7"
A	Φ178±2.0
D	8.5

Packing Quantity:2000pcs/Reel

Re-flowing Profile:

